

## LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC3444EDD#TRPBF

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2014-01-20 00:06:52)

TOTAL MASS (g): 0.023364

COMPONENT MATERIAL	VENDOR/INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL Pkg.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001534	1000000	65655.5078125	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.009350	975000	400181.875	
		Iron (Fe)	7439-89-6	0.000230	24000	9844.04589844	
		Phosphorus (P)	7723-14-0	0.000003	300	128.400619507	
		Zinc (Zn)	7440-66-6	0.000007	700	299.601409912	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-95-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		<b>Lead Frame Total:</b>			<b>0.009590</b>	<b>1000000</b>	<b>410453.90625</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.000437	1000000	18719.7558594	
		<b>External Plating Total:</b>			<b>0.000437</b>	<b>1000000</b>	<b>18719.7558594</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.000218	1000000	9130.44433594	
		<b>Internal Plating Total:</b>			<b>0.000218</b>	<b>1000000</b>	<b>9330.44433594</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000758	750000	3242.5507912	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.00253	250000	10829.4511719	
		<b>Die Attach Total:</b>			<b>0.003111</b>	<b>1000000</b>	<b>43271.0039062</b>
		Encapsulation	MULTIAROMATIC RESIN BOND FREE	Resin (EP)		0.001168	130000
Bromine (Br)	40093-93-8			0.000000	0	0	
Silica (SiO2)	60676-86-0			0.009047	860000	387213.40625	
Antimony Trioxide (Sb2O3)	1309-64-4			0.000000	0	0	
Metal Hydroxide				0.000000	0	0	
Carbon Black (C)	1333-86-4			0.000105	10000	4594.02099609	
<b>Encapsulation Total:</b>					<b>0.010320</b>	<b>1000000</b>	<b>450258.09375</b>
Bond Wire Estimated	AFW/TANAKA/Kn	Gold (Au)	7440-57-5	0.000054	1000000	2311.2109375	

TOTAL MASS (g): 0.023364